

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE 2800 MAIL ROOM

Applicant:

Serial No.:

09/737,407

Group Art Unit:

2883

Filed:

December 15, 2000

Entitled:

HIGH DENSITY ELECTRONIC INTERCONNECTION

June 15, 2001

Submission Under 37 CFR 1.98 (a) iii

Assistant Commissioner For Patents Washington, DC 20231

Sir:

Copies of the following pending applications that may contain material relevant to the above referenced application are submitted herewith in accordance with 37 CFR 1.98 (a) iii.

- Pace, US Appl'n No. 09/737,408, "Interconnection Method" (12/15/00) 1.
- Pace, US Appl'n No. 09/745,966, "Inverted Chip bonded Module" (12/22/00) 2.

A supplemental Information Disclosure Statement is also enclosed.

Respectfully submitted,

John F. McCormack,

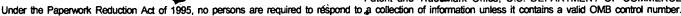
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